



Product Change Notification

106790 - 00

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Product Change Notification

Change Notification #: 106790 - 00
Change Title: MPFIM0001 Chassis Data Module Spare Part, PCN 106790-00, Product Design, Update Spare Part and Manufacturing Site
Date of Publication: September 21, 2006

Key Characteristics of the Change:

Product Design

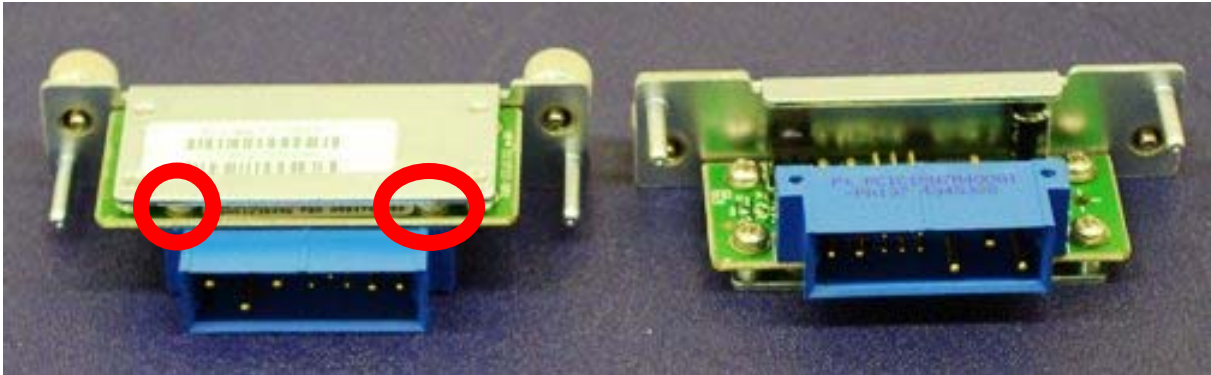
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Oct 16, 2006
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Description of Change to the Customer:

- 1.) Update to MPFIM0001 spare to reflect/incorporate the changes to the spare as described in the MPCHC0001 Chassis PCN105089 as shown in table 1.
- 2.) Manufacturing site transfers from the United States to Malaysia

Table 1.

Chassis Data Modules			
			
WAS	IS	DESCRIPTION	REASON FOR CHANGE
C14223-009	D14817-002	Chassis Data Module	Change to Overlay, PBA, and Firmware
C53314-002	C53314-003	Data Module FRU Overlay	Thicker Adhesive; reduce outside shape, deep notch added
A98474-104	A98474-201	FRU (CDM) PBA	Enhancing manufacturability and fit of boards to meet with redesigned chassis sheet metal; reduced hole registration; adding screws for Positronic connectors. Update FRU format to 109.FRU format also modified to reflect Product TA# of Backplane instead of CDM PBA in "Board" field, and TA# of chassis in "Product" and "Chassis" fields.
C14382-004	C14382-005	CDM Backing plate	Changed to improve cosmetics

Customer Impact of Change and Recommended Action:

No action required. Spare update identical to what is currently shipping in the MPCHC0001 chassis.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
MPFIM0001	849635	C14223-009	D14817-002

Reference Documents / Attachments:

Document: _____ Location #: _____

PCN Revision History:

Date of Revision: September 21, 2006	Revision Number: 00	Reason: Originally Published PCN
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